Title (en)

Gold base alloy for jewellery

Title (de)

Goldlegierung für Schmuckzwecke

Title (fr)

Alliage d'or pour la bijouterie

Publication

EP 0978572 A1 20000209 (DE)

Application

EP 99109579 A 19990514

Priority

DE 19834858 A 19980801

Abstract (en)

Gold alloy used for jewelry contains 70-80 % gold, 15-25 % copper and 0.1-0.5 % gallium.

Abstract (de)

Eine Goldlegierung für Schmuckzwecke enthält 70 bis 80 % Gold und 15 bis 25 % Kupfer. Die Legierung ist dadurch gekennzeichnet, daß sie 0,1 bis 5 % Gallium enthält.

IPC 1-7

C22C 5/02

IPC 8 full level

A44C 27/00 (2006.01); **C22C 5/02** (2006.01)

CPC (source: EP)

C22C 5/02 (2013.01)

Citation (search report)

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- [X] CHEMICAL ABSTRACTS, vol. 123, no. 12, 18 September 1995, Columbus, Ohio, US; abstract no. 150335, OUCHIDA, R. ET AL: "Effects of Au/Cu ratio and gallium content on the low-temperature age-hardening in Au-Cu-Ga alloys" XP002121973 & J. MATER. SCI. (1995), 30(15), 3863-6, XP002123010
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